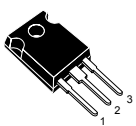
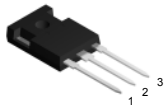


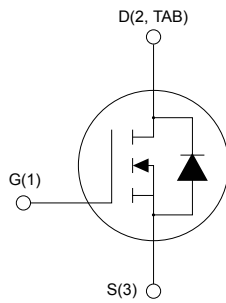
N-channel 950 V, 120 mΩ typ., 38 A, MDmesh DK5 Power MOSFETs in TO-247 and TO-247 long leads packages



TO-247



TO-247 long leads



AM01475v1_noZen



Features

| Order code | V_{DS} | $R_{DS(on)}$ max. | I_D |
|--------------|----------|-------------------|-------|
| STW40N95DK5 | 950 V | 130 mΩ | 38 A |
| STWA40N95DK5 | | | |

- Fast-recovery body diode
- Best $R_{DS(on)} \times \text{area}$
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness

Applications

- Switching applications

Description

These very high voltage N-channel Power MOSFETs are part of the MDmesh DK5 fast-recovery diode series. The MDmesh DK5 combines very low recovery charge (Q_{rr}) and recovery time (t_{rr}) with an excellent improvement in $R_{DS(on)}$ * area and one of the most effective switching behaviors, ideal for half bridge and full bridge converters.

Product status links

[STW40N95DK5](#)
[STWA40N95DK5](#)

Product summary

| | |
|------------|-------------------|
| Order code | STW40N95DK5 |
| Marking | 40N95DK5 |
| Package | TO-247 |
| Packing | Tube |
| Order code | STWA40N95DK5 |
| Marking | 40N95DK5 |
| Package | TO-247 long leads |
| Packing | Tube |

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|------------------|
| V_{GS} | Gate-source voltage | ± 30 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 38 | A |
| | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 24 | |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 152 | A |
| P_{TOT} | Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 450 | W |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 50 | V/ns |
| $dv/dt^{(3)}$ | MOSFET dv/dt ruggedness | 50 | V/ns |
| T_{stg} | Storage temperature range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating junction temperature range | | $^\circ\text{C}$ |

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 38\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DS} (\text{peak}) \leq V_{(BR)DSS}$, $V_{DD} = 760\text{ V}$.
3. $V_{DS} \leq 760\text{ V}$.

Table 2. Thermal data

| Symbol | Parameter | Value | Unit |
|------------|---|-------|---------------------------|
| R_{thJC} | Thermal resistance, junction-to-case | 0.28 | $^\circ\text{C}/\text{W}$ |
| R_{thJA} | Thermal resistance, junction-to-ambient | 50 | $^\circ\text{C}/\text{W}$ |

Table 3. Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------|--|-------|------|
| I_{AR} | Maximum current during repetitive or single pulse avalanche | 13 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | 730 | mJ |

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified.

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|---|------|------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$ | 950 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{GS} = 0\text{ V}$, $V_{DS} = 950\text{ V}$ | | | 1 | μA |
| | | $V_{GS} = 0\text{ V}$, $V_{DS} = 950\text{ V}$, $T_C = 125\text{ °C}^{(1)}$ | | | 100 | μA |
| I_{GSS} | Gate-source leakage current | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$ | | | ± 10 | μA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DD} = V_{GS}$, $I_D = 100\text{ }\mu\text{A}$ | 3 | 4 | 5 | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\text{ V}$, $I_D = 19\text{ A}$ | | 120 | 130 | m Ω |

1. Defined by design, not subject to production test.

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------|---------------------------------------|--|------|------|------|----------|
| C_{iss} | Input capacitance | $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$ | - | 3480 | - | pF |
| C_{oss} | Output capacitance | | - | 235 | - | pF |
| C_{rss} | Reverse transfer capacitance | | - | 2.3 | - | pF |
| $C_{o(tr)}^{(1)}$ | Equivalent capacitance time related | $V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ to }760\text{ V}$ | - | 371 | - | pF |
| $C_{o(er)}^{(2)}$ | Equivalent capacitance energy related | | - | 134 | - | pF |
| R_G | Intrinsic gate resistance | $f = 1\text{ MHz}$, $I_D = 0\text{ A}$ | - | 2 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 760\text{ V}$, $I_D = 38\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior) | - | 100 | - | nC |
| Q_{gs} | Gate source charge | | - | 19.5 | - | nC |
| Q_{gd} | Gate drain charge | | - | 67.6 | - | nC |

1. $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

2. $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DS} = 475\text{ V}$, $I_D = 19\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ | - | 30 | - | ns |
| t_r | Rise time | | - | 15 | - | ns |
| $t_{d(off)}$ | Turn-off delay time | (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform) | - | 82 | - | ns |
| t_f | Fall time | | - | 11 | - | ns |

Table 7. Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 38 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 152 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 38 \text{ A}, V_{GS} = 0 \text{ V}$ | - | | 1.5 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 19 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s},$ | - | 170 | | ns |
| Q_{rr} | Reverse recovery charge | $V_{DD} = 60 \text{ V}$ | - | 1.4 | | μC |
| I_{RRM} | Reverse recovery current | (see Figure 15. Test circuit for inductive load switching and diode recovery times) | - | 15 | | A |
| t_{rr} | Reverse recovery time | $I_{SD} = 19 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s},$ | - | 340 | | ns |
| Q_{rr} | Reverse recovery charge | $V_{DD} = 60 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$ | - | 5 | | μC |
| I_{RRM} | Reverse recovery current | (see Figure 15. Test circuit for inductive load switching and diode recovery times) | - | 30 | | A |

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

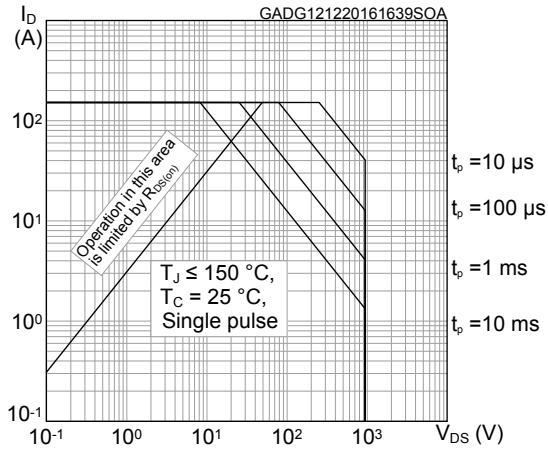
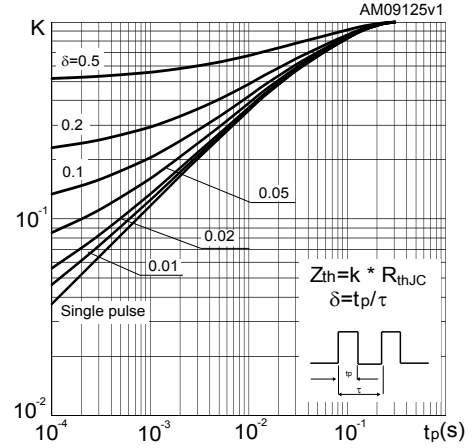
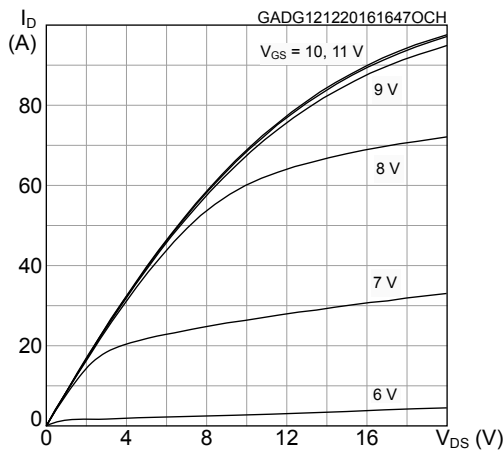
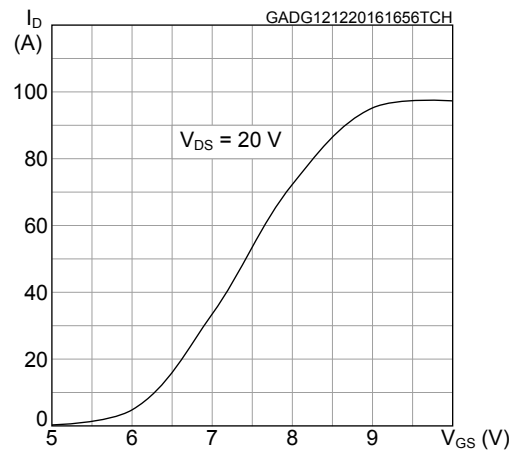
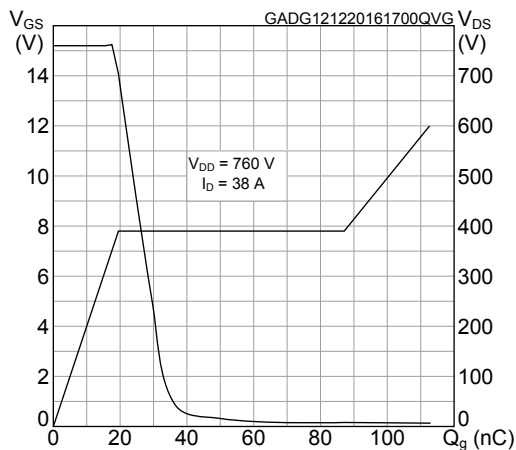
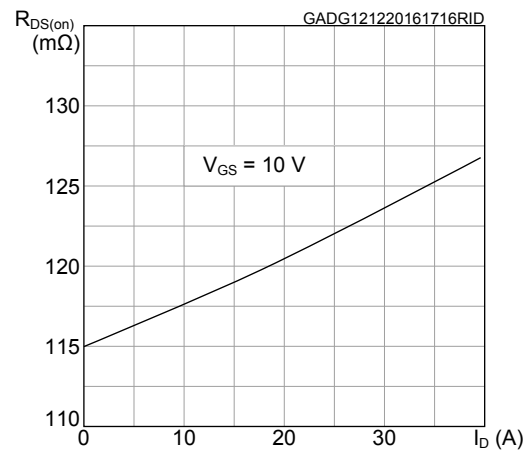
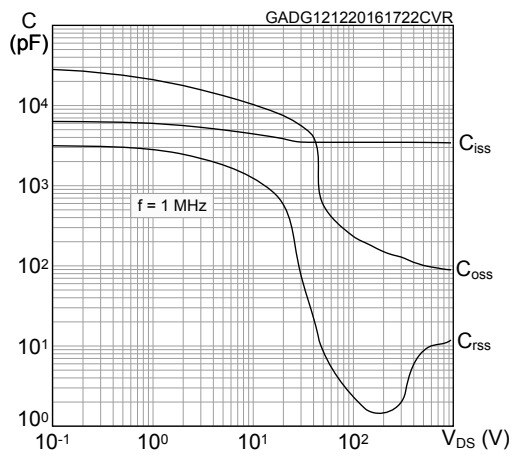
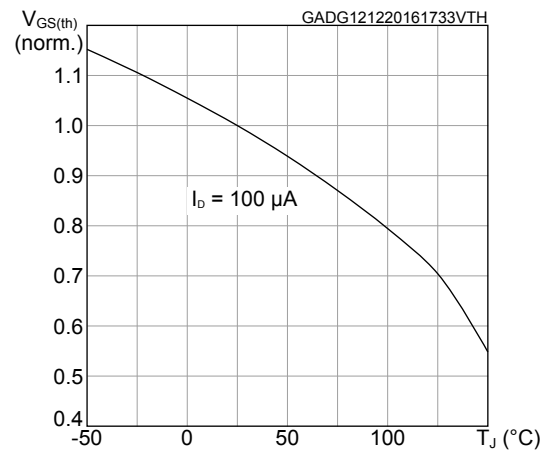
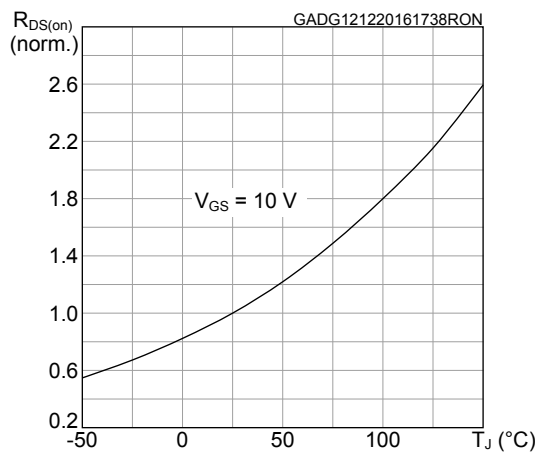
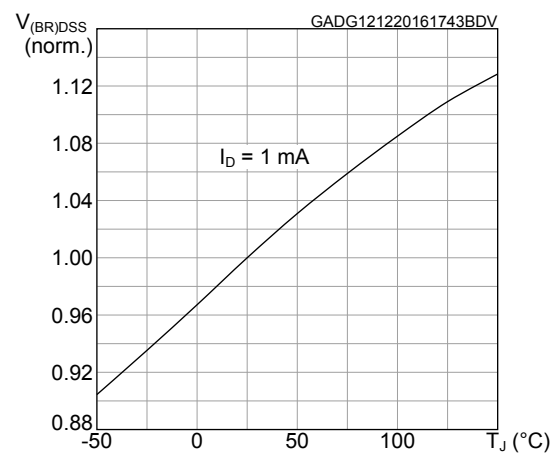
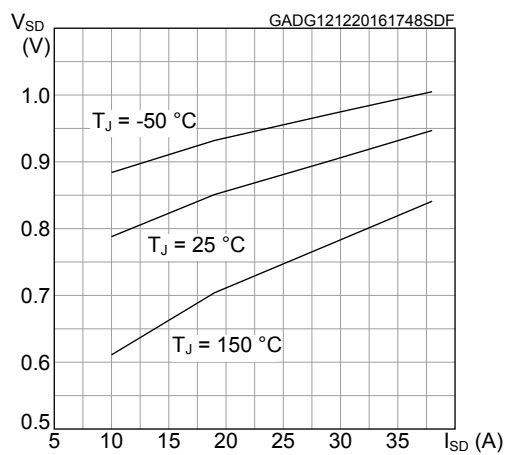
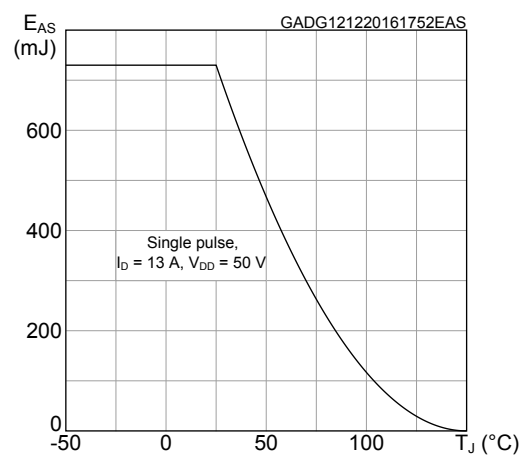
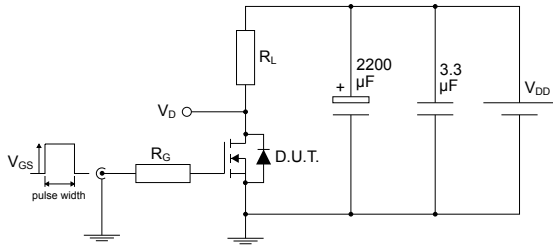
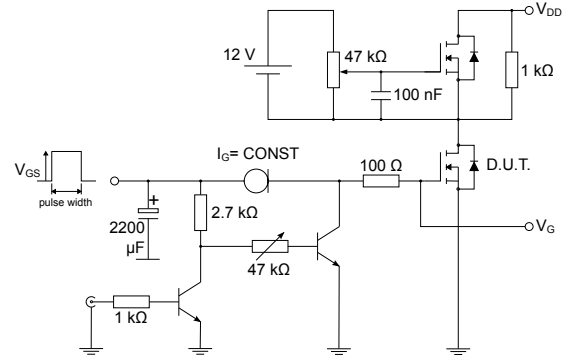
2.1 Electrical characteristics (curves)
Figure 1. Forward bias safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs gate-source voltage

Figure 6. Static drain-source on-resistance


Figure 7. Capacitance variations

Figure 8. Normalized gate threshold voltage vs temperature

Figure 9. Normalized on-resistance vs temperature

Figure 10. Normalized V_(BR)DSS vs temperature

Figure 11. Source-drain diode forward characteristics

Figure 12. Maximum avalanche energy vs starting T_J


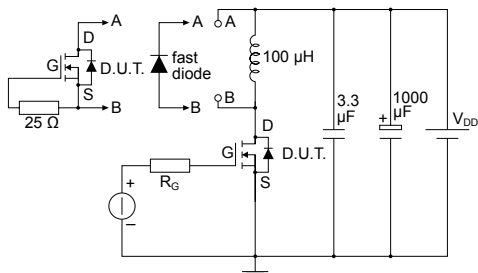
3 Test circuits

Figure 13. Test circuit for resistive load switching times


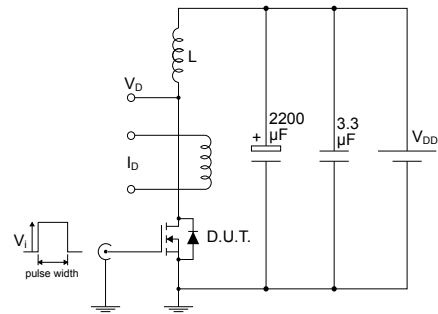
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Figure 14. Test circuit for gate charge behavior


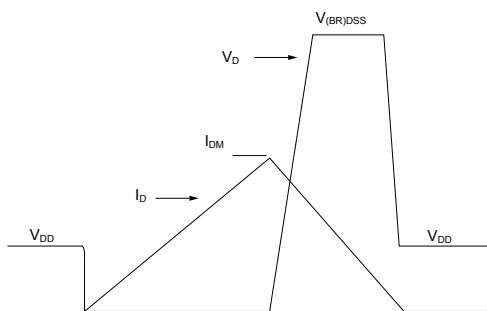
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Figure 15. Test circuit for inductive load switching and diode recovery times


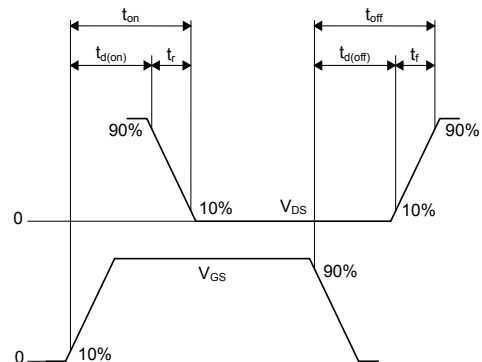
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Figure 16. Unclamped inductive load test circuit


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Figure 17. Unclamped inductive waveform


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Figure 18. Switching time waveform


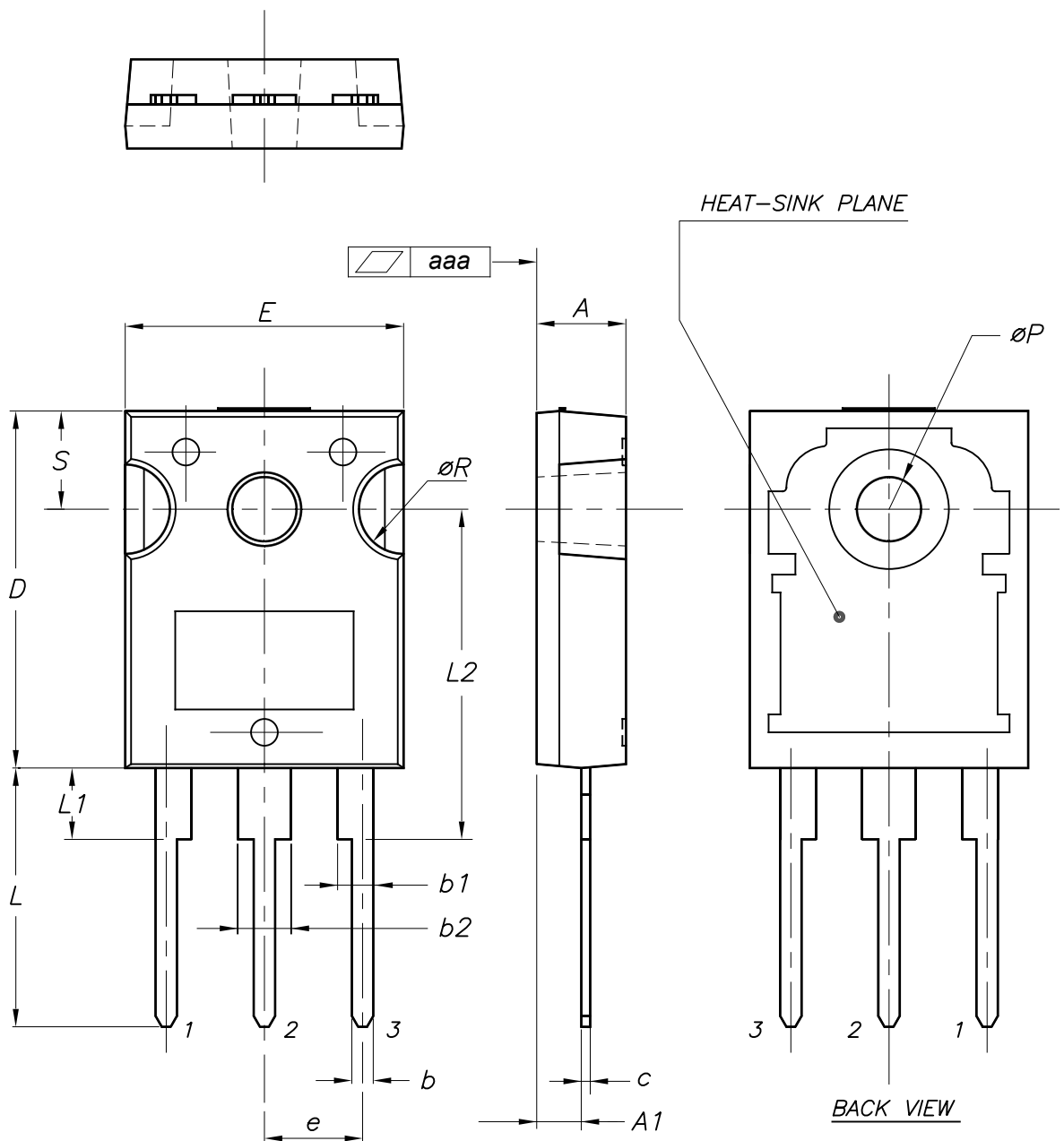
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-247 package information

Figure 19. TO-247 package outline



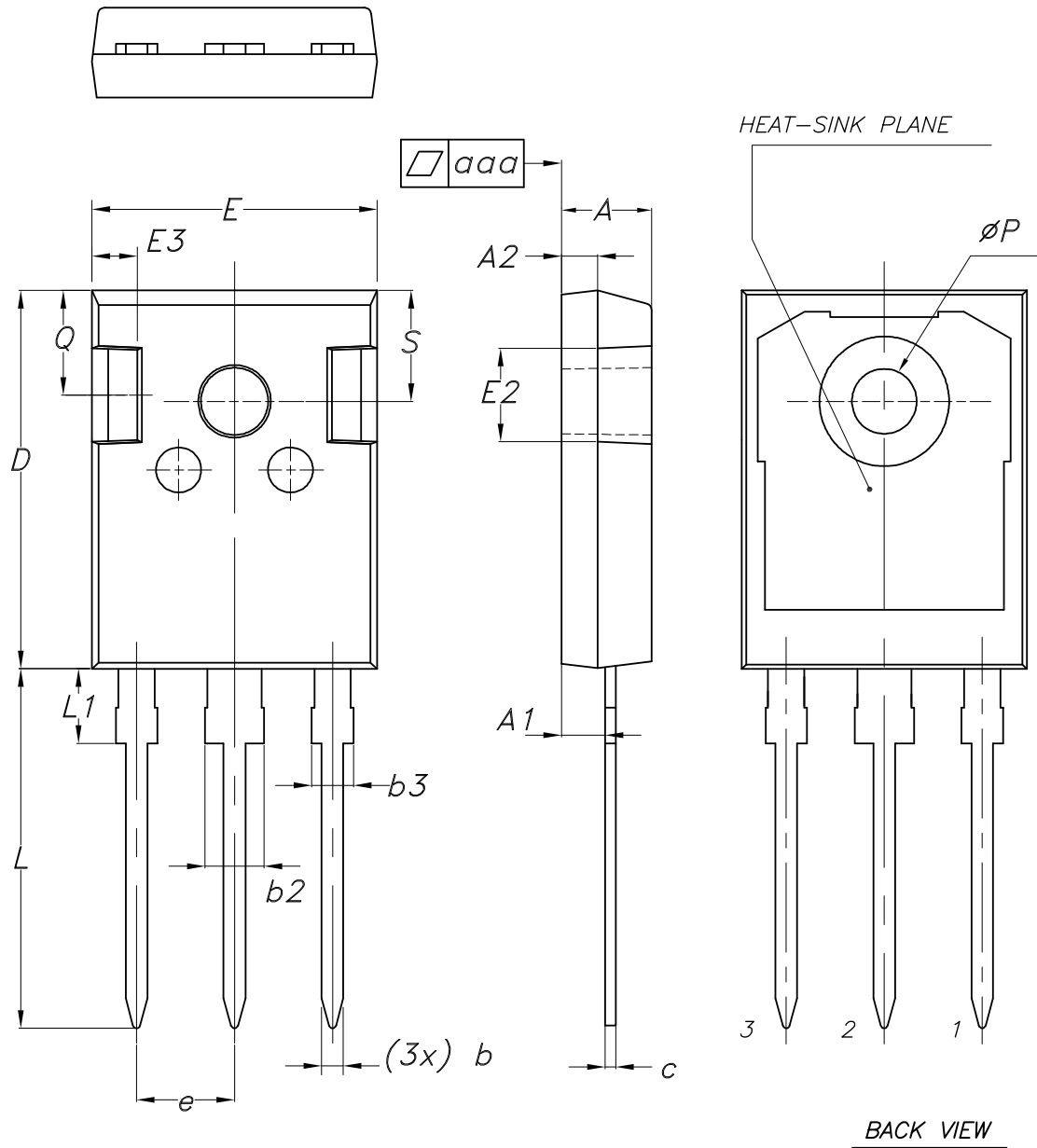
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Table 8. TO-247 package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.85 | | 5.15 |
| A1 | 2.20 | | 2.60 |
| b | 1.0 | | 1.40 |
| b1 | 2.0 | | 2.40 |
| b2 | 3.0 | | 3.40 |
| c | 0.40 | | 0.80 |
| D | 19.85 | | 20.15 |
| E | 15.45 | | 15.75 |
| e | 5.30 | 5.45 | 5.60 |
| L | 14.20 | | 14.80 |
| L1 | 3.70 | | 4.30 |
| L2 | | 18.50 | |
| ØP | 3.55 | | 3.65 |
| ØR | 4.50 | | 5.50 |
| S | 5.30 | 5.50 | 5.70 |
| aaa | | 0.04 | 0.10 |

4.2 TO-247 long leads package information

Figure 20. TO-247 long leads package outline



8463846_3

Table 9. TO-247 long leads package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.90 | 5.00 | 5.10 |
| A1 | 2.31 | 2.41 | 2.51 |
| A2 | 1.90 | 2.00 | 2.10 |
| b | 1.16 | | 1.26 |
| b2 | | | 3.25 |
| b3 | | | 2.25 |
| c | 0.59 | | 0.66 |
| D | 20.90 | 21.00 | 21.10 |
| E | 15.70 | 15.80 | 15.90 |
| E2 | 4.90 | 5.00 | 5.10 |
| E3 | 2.40 | 2.50 | 2.60 |
| e | 5.34 | 5.44 | 5.54 |
| L | 19.80 | 19.92 | 20.10 |
| L1 | | | 4.30 |
| P | 3.50 | 3.60 | 3.70 |
| Q | 5.60 | | 6.00 |
| S | 6.05 | 6.15 | 6.25 |
| aaa | | 0.04 | 0.10 |

Revision history

Table 10. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 19-Sep-2013 | 1 | First release. |
| 13-Nov-2015 | 2 | Updated title, features and description in cover page. Updated Section 10 : "Electrical characteristics" and Section 12.1:"TO-247 package information" Minor text changes. |
| 12-Apr-2016 | 3 | Updated title,silhouette and description in cover page. Updated <i>Table 2: "Absolute maximum ratings"</i> . Updated <i>Section 10: "Electrical characteristics"</i> . Added <i>Figure 21: "TO-247 long lead package outline"</i> . Minor text changes |
| 12-Dec-2016 | 4 | Datasheet status promoted from preliminary to production data. Updated document title on cover page. Updated <i>Table 2: "Absolute maximum ratings"</i> , <i>Table 4: "Thermal data"</i> , <i>Table 5: "On/off states"</i> , <i>Table 6: "Dynamic"</i> and <i>Table 8: "Source-drain diode"</i> . Added <i>Section 2.1: "Electrical characteristics (curves)"</i> . Minor text changes |
| 11-Aug-2021 | 5 | Updated Table 1. Absolute maximum ratings . Updated Section 4 Package information . Minor text changes. |

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